HexShield™ heat resistant material combines the benefits of honeycomb as a structural material with the additional benefits of formability with thermal resistance performance.
HexShield™ heat resistant material

HexShield™ 600 heat resistant material product description

- Optimized HHS-327-1/4-3.0 honeycomb as a carrier honeycomb
- Refractory material
  - 0.100 or 0.200 inch thickness
  - Weight = 0.26 psf
- Maximum size (to date) = 27x36 inches

HexShield™ heat resistant material is a new technology that provides high temperature resistance in aircraft engine nacelle applications and is made to be able to withstand a fire event. The technology builds on Hexcel’s long history of heat resistant honeycomb products with the 260°C/500°F HexWeb® HHS-327 honeycomb. It combines the benefits of honeycomb as a structural material with the additional benefits of formability with thermal resistance performance. This new technology can be combined with various facing materials to meet customer requirements.

Hexcel has created and completed testing on two different compositions HexShield™ 450 which performs well to a 450°F operating condition and HexShield™ 600 which performs well to a 600°F operating condition.

Initial customer qualification panels have already been successfully completed on the HexShield™ heat resistant material.

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